



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on) max}	I _D Τ _A = +25°C
	0.4Ω @ $V_{GS} = 4.5V$	1.5A
20V	0.5 Ω @ V _{GS} = 2.5V	1.3A
	0.7 Ω @ V _{GS} = 1.8V	1.1A

Features and Benefits

- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)}, 1.0V Max.
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surfaced Mount Package
- Ultra-Low Package Profile, 0.4mm Maximum Package Height
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power Management Functions

Mechanical Data

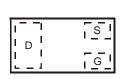
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (Approximate)



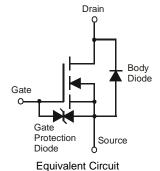




Bottom View



Top View Internal Schematic



Ordering Information (Note 4)

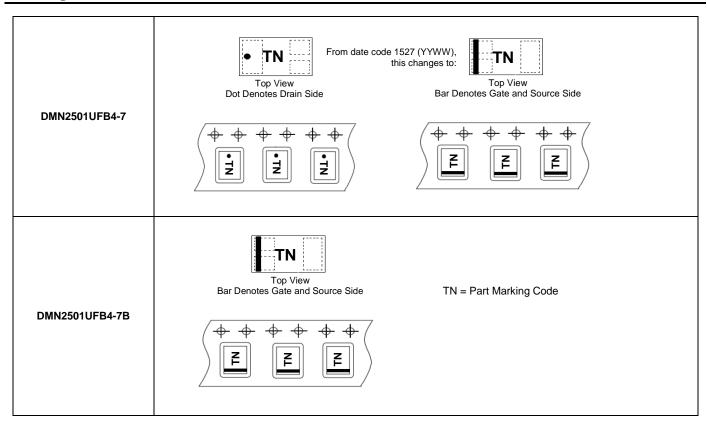
Part Number	Case	Packaging
DMN2501UFB4-7	X2-DFN1006-3	3,000/Tape & Reel
DMN2501UFB4-7B	X2-DFN1006-3	10.000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.



Marking Information



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	20	V		
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Durin Comment (Note 5) V	Steady State	T _A = 25°C T _A = 70°C	I _D	1.0 0.8	А
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t<10s	T _A = 25°C T _A = 70°C	I _D	1.2 0.9	А
Continuous Durin Comment (Note C) V	Steady State	T _A = 25°C T _A = 70°C	I _D	1.5 1.2	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t<10s	T _A = 25°C T _A = 70°C	I _D	1.8 1.4	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	6	Α
Maximum Body Diode continuous Current			Is	1	Α

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

	Symbol	Value	Units
$T_A = +25$ °C	D-	0.5	W
$T_A = +70^{\circ}C$	PD	0.3	
Steady State	D	251	°C/W
t<10s	K _θ JA	188	
$T_A = +25$ °C	D-	1.2	W
$T_A = +70^{\circ}C$	PD	0.7	
Steady State	D	110	°C/W
t<10s	$\kappa_{ heta}$ JA	82	
	$T_{J_i} T_{STG}$	-55 to +150	°C
	$T_A = +70^{\circ}C$ Steady State $t<10s$ $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ Steady State	$\begin{array}{c c} T_A = +25^{\circ}C \\ T_A = +70^{\circ}C \\ \hline Steady State \\ t<10s \\ \hline T_A = +25^{\circ}C \\ \hline T_A = +70^{\circ}C \\ \hline Steady State \\ t<10s \\ \hline \end{array} \begin{array}{c} P_D \\ \hline P_D \\ \hline R_{\theta JA} \\ \hline \end{array}$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.



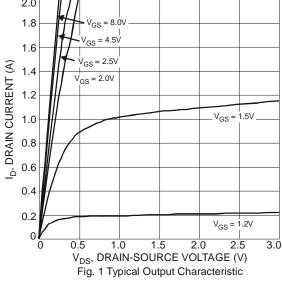
Electrical Characteristics (@ $T_A = \pm 25$ °C, unless otherwise specified.)

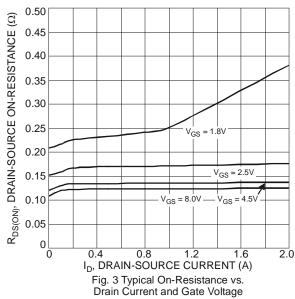
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	100	nA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±1	μΑ	$V_{GS} = \pm 6V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(th)}	0.5	0.76	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
			170	400		$V_{GS} = 4.5V, I_D = 600mA$	
Static Drain-Source On-Resistance	R _{DS} (ON)	-	200	500	$m\Omega$	$V_{GS} = 2.5V, I_D = 500mA$	
			260	700		$V_{GS} = 1.8V, I_D = 350mA$	
Forward Transfer Admittance	Y _{fs}	-	1.4	-	S	$V_{DS} = 10V, I_D = 400mA$	
Diode Forward Voltage	V_{SD}		0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	-	82	-	pF	101/1/	
Output Capacitance	Coss	•	12	-	pF	$V_{DS} = 16V, V_{GS} = 0V,$ -f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	10	-	pF	71 = 1.0WH2	
Gate resistance	Rg	-	83	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	-	1.1	-	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	-	2.0	-	nC	\/ 40\/ L 250** A	
Gate-Source Charge	Qgs	-	0.14	-	nC	$V_{DS} = 10V, I_{D} = 250mA$	
Gate-Drain Charge	Q _{gd}	-	0.19	-	nC		
Turn-On Delay Time	t _{D(on)}	-	6.6	-	ns		
Turn-On Rise Time	t _r	-	6.4	-	ns	$\begin{array}{l} V_{DD} = 10V, V_{GS} = 4.5V, \\ -R_L = 47\Omega, R_G = 10\Omega, \\ -I_D = 200 \text{mA} \end{array}$	
Turn-Off Delay Time	t _{D(off)}	-	40.4	-	ns		
Turn-Off Fall Time	tf	-	17.3	-	ns		

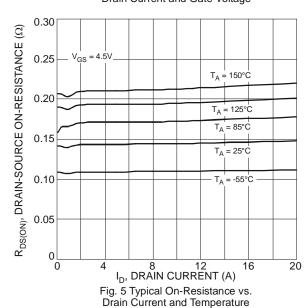
Notes:

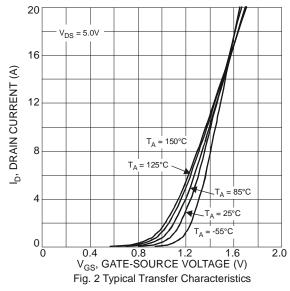
^{7.} Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.

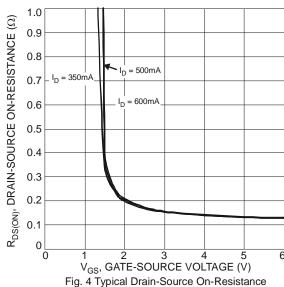












vs. Gate-Source Voltage

1.8

1.8

V_{GS} = 4.5V

V_D = 1.0A

V_{SS} = 8.0V

I_D = 1.A

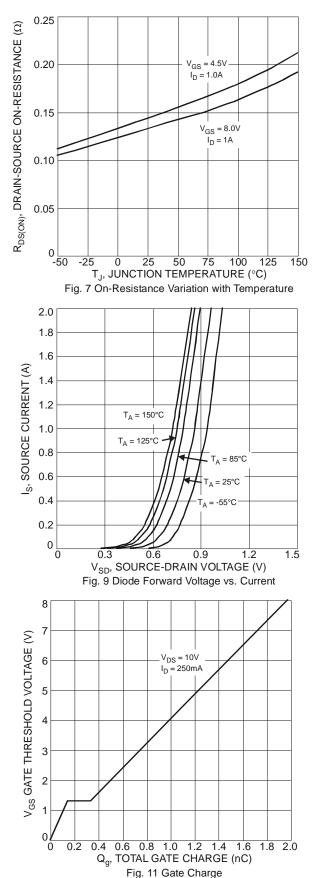
V_{SS} = 8.0V

I_D = 1.A

V_{SS} = 8.0V

I_D = 1.A





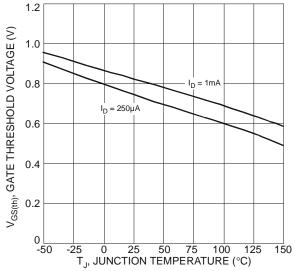
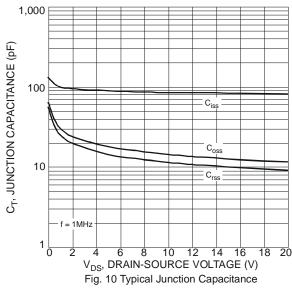
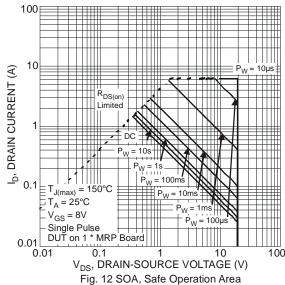
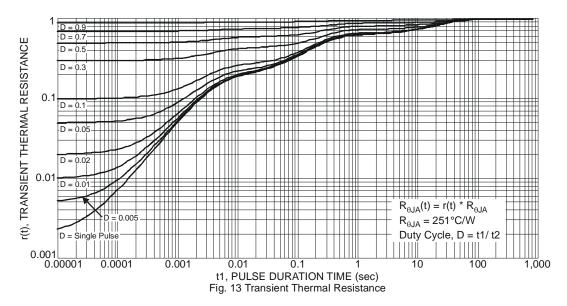


Fig. 8 Gate Threshold Variation vs. Ambient Temperature



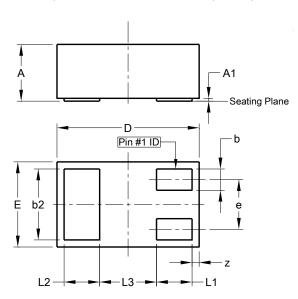






Package Outline Dimensions

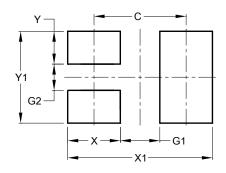
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



X2-DFN1006-3					
Dim	Min	Max	Тур		
Α		0.40	_		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.05	1.00		
Е	0.55	0.65	0.60		
е	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70



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